



Design, Fabrication, Testing of MEMS/NEMS

Guest Editors:

Dr. Nan Wang

Dr. Tao Wu

Dr. Jicong Zhao

Dr. Chen Liu

Deadline for manuscript
submissions:

closed (30 December 2022)

Message from the Guest Editors

Dear Colleagues,

Here, we would like to introduce the special issue of "Design, Fabrication, Testing of MEMS/NEMS" and encourage our colleagues to contribute their excellent work to this Special Issue. This Special Issue aims to highlight recent novel progresses in cutting-edge MEMS device technologies, including original research articles and topical reviews in the scope of materials, design and fabrication technologies, characterization methods, packaging and microsystem integration solutions.

The topics of this Special Issue include, but are not limited to:

1. Novel functional MEMS materials;
2. Innovative MEMS mechanical and chemical sensors;
3. Biological devices for wearable healthcare systems;
4. Optical and quantum MEMS devices and systems;
5. RF MEMS for telecommunication systems;
6. MEMS devices for self-powered systems;
7. Micro/nano fabrication process and integration;
8. MEMS packaging and reliability issues.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, dblp, and other databases.

Journal Rank: JCR - Q2 (*Physics, Applied*) / CiteScore - Q2 (*Mechanical Engineering*)

Contact Us

Micromachines Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/micromachines
micromachines@mdpi.com
[X@micromach_mdpi](https://twitter.com/micromach_mdpi)